

TYPICAL DEVICE CHARACTERISTICS

MAXIMUM RATINGS @ 25°C Unless Otherwise Specified

PARAMETER	SYMBOL	VALUE	UNITS
Peak Pulse Power (tp = 8/20μs) - See Figure 1	P _{PP}	100	Watts
Operating Temperature	T _L	-55 to 150	°C
Storage Temperature	T _{STG}	-55 to 150	°C

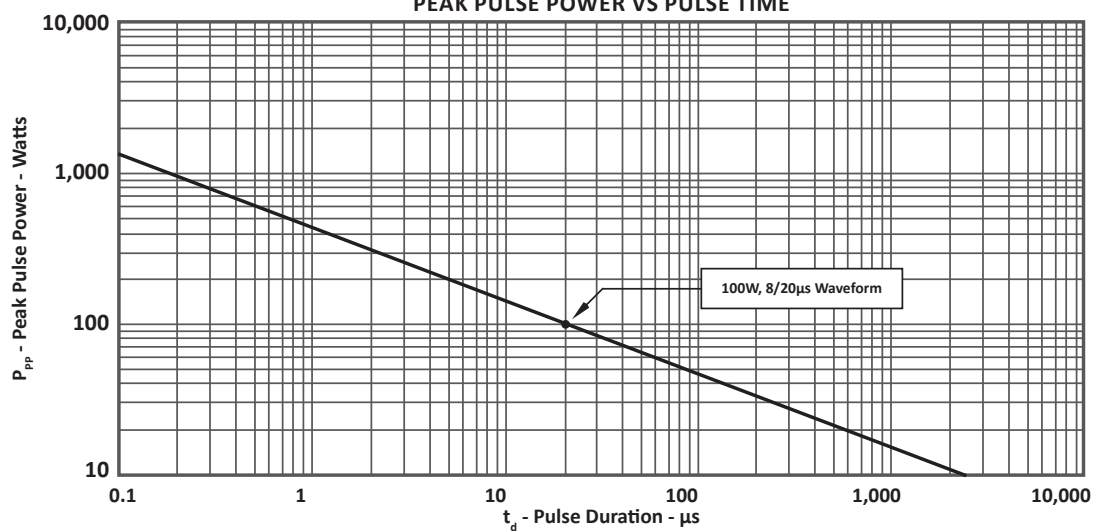
ELECTRICAL CHARACTERISTICS PER LINE @ 25°C Unless Otherwise Specified

PART NUMBER	DEVICE MARKING	RATED STAND-OFF VOLTAGE V _{WM} VOLTS	MINIMUM BREAKDOWN VOLTAGE @ 1mA V _(BR) VOLTS	MAXIMUM CLAMPING VOLTAGE (Fig. 2) @ I _p = 5A V _c VOLTS	MAXIMUM LEAKAGE CURRENT @ V _{WM} I _d μA	MAXIMUM CAPACITANCE (Note 1) @ 0V, 1MHz C _j pF
SMF05C	05C	5.0	6.0	9.8	5	60
SMF12C	12C	12.0	13.3	18.0	1	30
SMF15C	15C	15.0	16.7	22.0	1	25
SMF24C	24C	24.0	26.7	50.0	1	20

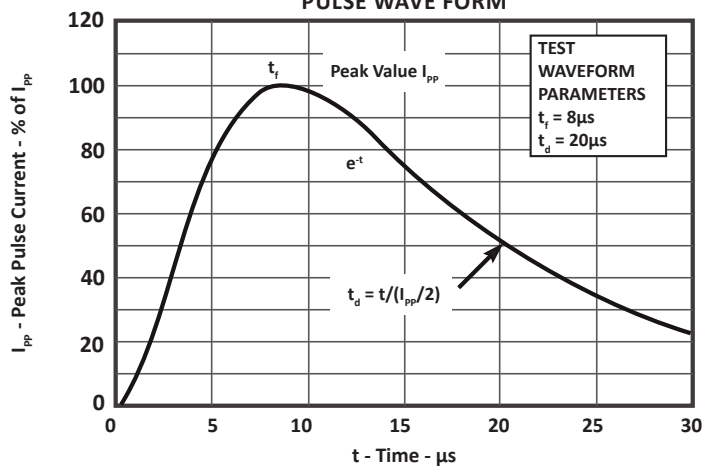
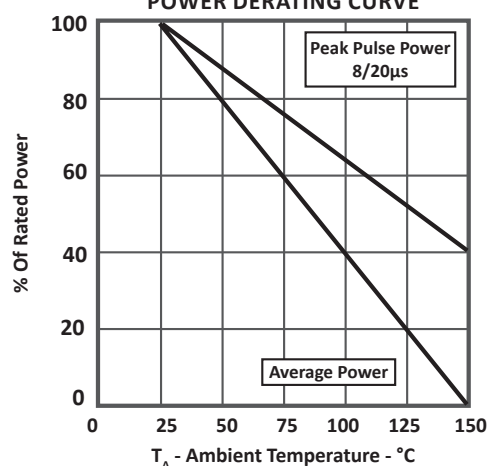
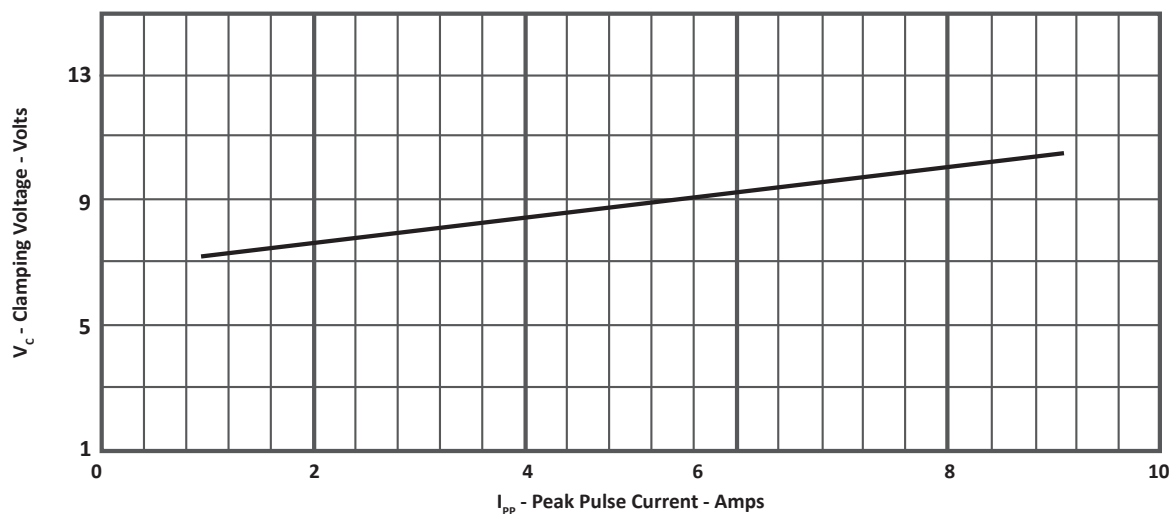
NOTES

1. Pins 1, 3, 4, 5 or 6 to pin 2.

FIGURE 1
PEAK PULSE POWER VS PULSE TIME



TYPICAL DEVICE CHARACTERISTICS

 FIGURE 2
 PULSE WAVE FORM

 FIGURE 3
 POWER DERATING CURVE

 FIGURE 4
 TYPICAL CLAMPING VOLTAGE VS PEAK PULSE CURRENT SMF05C


APPLICATION INFORMATION

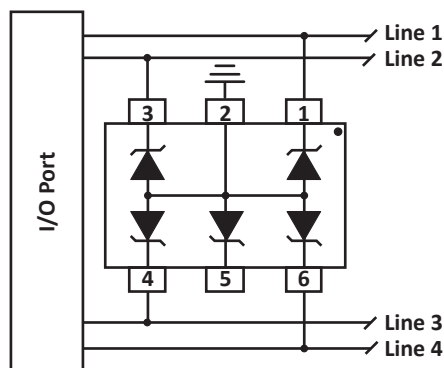


FIGURE 1 - COMMON-MODE I/O PORT PROTECTION (UNIDIRECTIONAL)

Circuit connectivity is as follows:

- Line 1 connected to pin 1.
- Line 2 connected to pin 3.
- Line 3 connected to pin 4.
- Line 4 connected to pin 6.
- Pin 2 connected to ground.
- Pin 5 not connected.

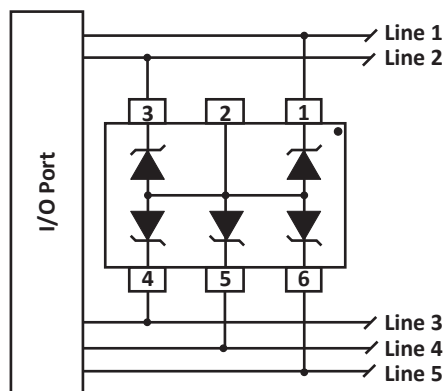


FIGURE 2 - COMMON-MODE I/O PORT PROTECTION (BIDIRECTIONAL)

Circuit connectivity is as follows:

- Line 1 connected to pin 1.
- Line 2 connected to pin 3.
- Line 3 connected to pin 4.
- Line 4 connected to pin 5.
- Line 5 connected to pin 6.
- Pin 2 not connected.

CIRCUIT BOARD RECOMMENDATIONS

Circuit board layout is critical for electromagnetic compatibility protection. The following guidelines are recommended:

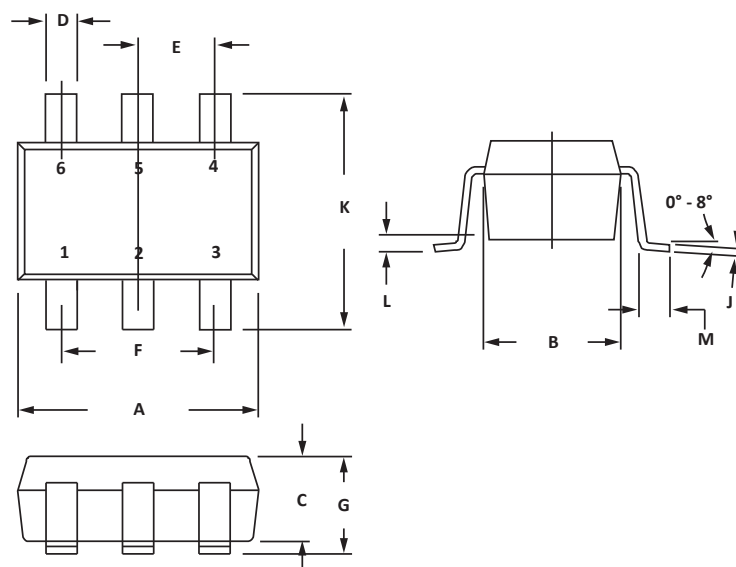
- The protection device should be placed near the input terminals or connectors, the device will divert the transient current immediately before it can be coupled into the nearby traces.
- The path length between the TVS device and the protected line should be minimized.
- All conductive loops including power and ground loops should be minimized.
- The transient current return path to ground should be kept as short as possible to reduce parasitic inductance.
- Ground planes should be used whenever possible. For multilayer PCBs, use ground vias.

SC70-6L PACKAGE INFORMATION

OUTLINE DIMENSIONS				
DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.90	2.15	0.074	0.084
B	1.15	1.35	0.045	0.055
C	0.80	1.00	0.031	0.040
D	0.15	0.30	0.005	0.012
E	0.65 BSC		0.026 BSC	
F	1.30 BSC		0.051 BSC	
G	0.80	1.10	0.031	0.043
J	0.08	0.25	0.003	0.010
K	2.00	2.40	0.078	0.095
L	-	0.10	-	0.004
M	0.26	0.46	0.010	0.018

NOTES

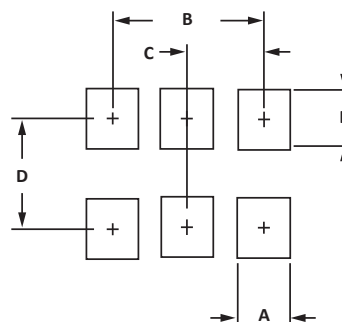
1. Controlling dimension: inches.
2. Dimensioning and tolerances per ANSI Y14.5M, 1985.
3. Dimensions are exclusive of mold flash and metal burrs.



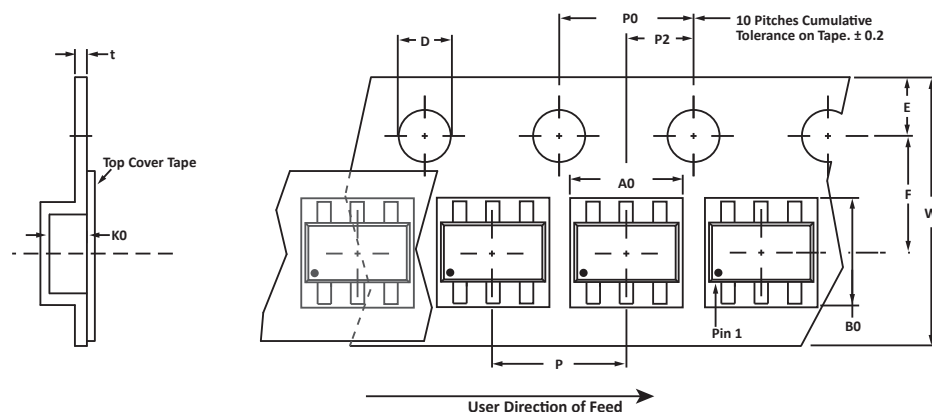
PAD LAYOUT DIMENSIONS		
DIM	MILLIMETERS	INCHES
	NOMINAL	NOMINAL
A	0.50	0.020
B	1.30	0.051
C	0.65	0.026
D	1.72	0.068
E	0.60	0.024

NOTES

1. Controlling dimension: inches.



TAPE AND REEL



SPECIFICATIONS

REEL DIA.	TAPE WIDTH	A0	B0	K0	D	E	F	W	P0	P2	P	tmax
178mm (7")	8mm	2.25 ± 0.10	2.34 ± 0.10	1.22 ± 0.10	1.50 ± 0.10	1.75 ± 0.10	3.50 ± 0.05	8.00 ± 0.30	4.00 ± 0.10	2.00 ± 0.05	4.00 ± 0.10	0.25

NOTES

1. Dimensions are in millimeters.
2. Surface mount product is taped and reeled in accordance with EIA-481.
3. Suffix - T7 = 7" Reel - 3,000 pieces per 8mm tape.
4. Marking on Part - marking code (see page 2) and pin one defined by dot on package.

ORDERING INFORMATION

BASE PART NUMBER (xx = Voltage)	LEADFREE SUFFIX	TAPE SUFFIX	QTY/REEL	REEL SIZE	TUBE QTY
SMFxxC	-LF	-T7	3,000	7"	n/a

This device is only available in a Lead-Free configuration.

COMPANY INFORMATION

COMPANY PROFILE

In business more than 25 years, ProTek Devices™ is a privately held semiconductor company. The company offers a product line of overvoltage protection and overcurrent protection components. These include transient voltage suppressor array (TVS arrays) avalanche breakdown diode, steering diode TVS array and electronics SMD chip fuses. These components deliver circuit protection in electronic systems from numerous overvoltage and overcurrent events. They include lightning; electrostatic discharge (ESD); nuclear electromagnetic pulses (NEMP); inductive switching; and electromagnetic interference (EMI) / radio frequency interference (RFI). ProTek Devices also offers LED wafer die for ESD protection and related high frequency products. ProTek Devices is ISO 9001:2015 certified.

CONTACT US

Corporate Headquarters

2929 South Fair Lane
Tempe, Arizona 85282
USA

By Telephone

General: 602-431-8101
Sales: & Marketing: 602-414-5109
Customer Service: 602-414-5114
Product Technical Support: 602-414-5107

By Fax

General: 602-431-2288

By E-mail:

Asia Sales: asiasales@protekdevices.com
Europe Sales: europesales@protekdevices.com
U.S. Sales: ussales@protekdevices.com
Distributor Sales: distysales@protekdevices.com
Customer Service: service@protekdevices.com
Technical Support: support@protekdevices.com

ProTek Devices (Asia Pacific) Pte. Ltd.

8 Ubi Road 2, #06-19
Zervex
Singapore - 408538
Tel: +65-67488312
Fax: +65-67488313

Web

www.protekdevices.com

COPYRIGHT © ProTek Devices 2001 - This literature is subject to all applicable copyright laws and is not for resale in any manner.

SPECIFICATIONS: ProTek reserves the right to change the electrical and or mechanical characteristics described herein without notice.

DESIGN CHANGES: ProTek reserves the right to discontinue product lines without notice and that the final judgement concerning selection and specifications is the buyer's and that in furnishing engineering and technical assistance. ProTek assumes no responsibility with respect to the selection or specifications of such products. ProTek makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ProTek assume any liability arising out of the application or use of any product or circuit and specifically disclaims any and all liability without limitation special, consequential or incidental damages.

LIFE SUPPORT POLICY: ProTek Devices products are not authorized for use in life support systems without written consent from the factory.